

ABSTRACT

An optical device package includes a substrate; an optical fiber, a frame, and optionally a lid and an optical semiconductor component. The upper surface of the frame includes conductive vias extending vertically to solder balls on its upper surface. Conductive traces along the surface of the substrate provide electrical communication between the optical semiconductor component and the frame. The optical device package is adapted for flip-chip type mounting to a circuit board or other mounting surface.

5

10

0

0

0

0

0

0

0

0

0

0

0

0

0

0

0

0

0

0

0

0

0

0

0

0

0

0

0

0

0

0

0

0

0

0

0

0

0

0

0